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Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-10-16
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNSR*F62G81B	A	ZA41	2014-10-16
Amount	UoM	Unit type	ST ECOPACK Grade	
70.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	4.3X2.77X2	NAC	J bend	
Comment	SMA; Md valid for CP: STTH1L06A.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNSR*F62G81B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	0.807	mg	supplier	DIE	Silicon (Si)	7440-21-3		0.789	mg	977695	11271
SILICON DIE				supplier	METALLIZATION	Aluminium (Al)	7429-90-5		0.005	mg	6196	71
SILICON DIE				supplier	METALLIZATION	Gamma-butyrolactone	96-48-0		0.005	mg	6196	71
SILICON DIE				supplier	PASSIVATION	Polyhydroxyamide	55295-98-2		0.002	mg	2478	29
SILICON DIE				supplier	PASSIVATION	Gold (Au)	7440-57-5		0.001	mg	1239	14
SILICON DIE				supplier	BACK SIDE METALIZATION	Nickel (Ni)	7440-02-0		0.005	mg	6196	71
Die attach	Other organic material	2.849	mg	Supplier	soft solder	Ag	7440-22-4		0.071	mg	24921	1014
Die attach				Supplier	soft solder	Sn	7440-31-5		0.143	mg	50193	2043
Die attach				Supplier	soft solder	Lead	7439-92-1	7a-Lead in high me	2.635	mg	924886	37643
Leadframe	Copper and its alloy	26.893	mg	Supplier	Alloy	Cu	7440-50-8		26.88	mg	999517	384000
Leadframe				Supplier	Alloy	Zn	7440-66-6		0.001	mg	37	14
Leadframe				Supplier	Alloy	Fe	7439-89-6		0.003	mg	112	43
Leadframe				Supplier	Alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	335	129
Encapsulation	Other organic material	38.81	mg	Supplier	Molding Compound	silica fused	7631-86-9		26.662	mg	686988	380886
Encapsulation				Supplier	Molding Compound	silica quartz	14808-60-7		9.703	mg	250013	138614
Encapsulation				Supplier	Molding Compound	phenolic resin	9003-35-4		2.328	mg	59985	33257
Encapsulation				Supplier	Molding Compound	carbon black	1333-86-4		0.117	mg	3015	1671
Finishing	Other inorganic material	0.641	mg	Supplier	connection coating	Sn	7440-31-5		0.641	mg	1000000	9157